

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>HIROAKI NAKANO</td> <td>11/11/2013</td> </tr> <tr> <td>SHINICHI FUKUDA</td> <td>11/11/2013</td> </tr> <tr> <td>YUJI MURAYAMA</td> <td>11/20/2013</td> </tr> <tr> <td>KENICHI FUJIMAKI</td> <td>11/11/2013</td> </tr> <tr> <td>TOMOMICHI MURAKAMI</td> <td>11/14/2013</td> </tr> </tbody> </table>		Name	Execution Date	HIROAKI NAKANO	11/11/2013	SHINICHI FUKUDA	11/11/2013	YUJI MURAYAMA	11/20/2013	KENICHI FUJIMAKI	11/11/2013	TOMOMICHI MURAKAMI	11/14/2013
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<table border="1"> <tr> <td>Name:</td> <td>SONY CORPORATION</td> </tr> <tr> <td>Street Address:</td> <td>1-7-1 KONAN, MINATO-KU</td> </tr> <tr> <td>City:</td> <td>TOKYO</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>108-0075</td> </tr> </table>		Name:	SONY CORPORATION	Street Address:	1-7-1 KONAN, MINATO-KU	City:	TOKYO	State/Country:	JAPAN	Postal Code:	108-0075		
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CORRESPONDENCE DATA													
Fax Number:	(312)876-7934												
Phone:	3128767925												
Email:	patents.us@dentons.com												
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>													
Correspondent Name:	DENTONS US LLP												
Address Line 1:	P.O. BOX 061080												
Address Line 4:	CHICAGO, ILLINOIS 60606-1080												
ATTORNEY DOCKET NUMBER:	09792909-8759												
NAME OF SUBMITTER:	SUSAN FARLEY												

Signature:	/susan farley/
Date:	12/17/2013
Total Attachments: 2 source=Assignment20131217#page1.tif source=Assignment20131217#page2.tif	

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in
ENERGY RECEIVER, DETECTION METHOD, POWER TRANSMISSION SYSTEM, DETECTION DEVICE, AND ENERGY TRANSMITTER

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Application No.: PCT/JP2012/067739 International Filing Date: 2012/07/02

This assignment executed on the dates indicated below.

HIROAKI NAKANO Name of first or sole inventor	Execution date of U.S. Patent Application
TOKYO, JAPAN Residence of First or sole inventor	
<u>Hiroaki Nakano</u> Signature of first or sole inventor	<u>November 11, 2013</u> Date of this assignment

SHINICHI FUKUDA Name of second inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN Residence of second inventor	
<u>Shinichi Fukuda</u> Signature of second inventor	<u>November 11, 2013</u> Date of this assignment

YUJI MURAYAMA Name of third inventor	Execution date of U.S. Patent Application
TOKYO, JAPAN Residence of third inventor	
<u>Yuji Murayama</u> Signature of third inventor	<u>November 20, 2012</u> Date of this assignment

ADDITIONAL INVENTOR(S)

KENICHI FUJIMAKI

Name of fourth inventor

KANAGAWA, JAPAN

Residence of fourth inventor

K. Fujimaki

Signature of fourth inventor

Execution date of U.S. Patent Application

November 11, 2013

Date of this assignment

TOMOMICHI MURAKAMI

Name of fifth inventor

TOKYO, JAPAN

Residence of fifth inventor

Tomomichi Murakami

Signature of fifth inventor

Execution date of U.S. Patent Application

November 14, 2013

Date of this assignment

Name of sixth inventor

Execution date of U.S. Patent Application

Residence of sixth inventor

Signature of sixth inventor

Date of this assignment

Name of seventh inventor

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